

3230

双轴全自动减薄机

Dual spindle fully automatic grinder



GLTECH
光力科技

ADT
Advanced Dicing Technologies

ADT3230是一款由GLTECH旗下英国Loadpoint、ADT联合研发的高精度、高稳定、高效率的双主轴三位全自动减薄机。适用于8/12寸常见硅基半导体材料的加工。

ADT3230 owns performance of high precision, high stability, high efficiency, which is a fully automatic thinning grinder with properties of 2 axis and 3 chuck tables, jointly developed by Loadpoint and ADT under GLTECH. It is suitable for processing 8/12 inch common silicon-based semiconductor materials.

ADT3230由搬运及研磨两部分组成。ADT3230搭载Loadpoint设计制造的高稳定、高刚度、大功率主轴。相对业界同类机型，具有更高的研磨效率和对超硬材料适应性。首次在业界同类机型中采用高稳定性、高刚性气浮工作台，可满足对精度要求更高的研磨需求。

ADT3230 consists of handling and grinding, which is equipped with a high stability, static stiffness, and high-power spindle designed and manufactured by Loadpoint. Compared with others in the industry, it has higher grinding efficiency and adaptability to superhard material. It is the first time to adopt a highly stable and rigid air flotation workbench in this industry among similar models, which can meet better precision grinding requirements.

ADT3230奉行可靠稳定、全程洁净、操作便捷的设计理念。设备继承了ADT产品稳定可靠的特点，传承了Loadpoint对精度的追求，适配了行业的应用习惯和特点，操作软件可对特定行业定制。

ADT3230 adheres to the design concept of reliability, stability, complete cleanliness, and facile operation. This device inherits stable and reliable performances of ADT, pursuit of precision of Loadpoint, and adapts to industry application habits and performance. Software can be customized for specific industries.

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规格 Items

设备型号	ADT3230
基本参数	
工作模式	全自动、半自动
结构形式	2主轴, 3工作台
磨削方式	垂直进给
片内厚度差	$\leq 1.5 \mu\text{m}$ ($\varnothing 200$) / $\leq 3 \mu\text{m}$ ($\varnothing 300$)
片间厚度差	$\pm 3 \mu\text{m}$
效率	理论24片 (研磨前厚度750 μm , 研磨后厚度300 μm)
可加工物料	
可加工晶圆直径	8/12寸
可加工物料厚度	<2mm
物料种类	常见硅基半导体材料
主轴	
轴承类型	气浮轴承
主轴数量	2
主轴功率	6.3 kW (标配)、11kW (选配)
转速	1000~4000 rpm
Z轴	
Z轴行程	120mm
Z轴进刀速度	0.0001~0.080mm/s
Z轴快速进刀速度	50mm/s
Z轴最小位移	0.1 μm
Z轴分辨率	0.1 μm
工作台	
轴承类型	气浮轴承
工作台形式	多孔陶瓷工作台
物料夹持方式	真空
数量	3
旋转速度	0~300 rpm(CCW/CW)
清洗方式	毛刷清洗/油石清洗
气浮转台	
转速	0~300 rpm(CCW/CW)
支承方式	静压气浮
定位精度	0.1°
高度计	
测量范围	0~2 mm
分辨率	0.1 μm
重复精度	$\pm 0.5 \mu\text{m}$
设备外形尺寸	
(宽×深×高)/mm	1415×3325×1820
设备重量	4.6t

Machine Model	ADT3230
Basics	
Models	Fully automatic\automatic
Structures	2 spindles\3 chuck table
Grinding Method	vertical feed
Total thickness variation	$\leq 1.5 \mu\text{m}$ ($\varnothing 200$) / $\leq 3 \mu\text{m}$ ($\varnothing 300$)
Thickness variation	$\pm 3 \mu\text{m}$
Efficiency	24pieces in theory (before grinding:750 μm , after grinding:300 μm)
Compatible material	
Wafer diameter	8/12 inch
Thickness	< 2 mm
Type of material	Common silicon-based semiconductor materials
Spindle	
Bearing type	Air spindle
Number of spindle axis	2
Power	6.3 kW (standard) 、 11 kW (options)
Rotative speed	1000 ~ 4000 rpm
Z Axis	
Z axis vertical stroke	120mm
Z-axis vertical feed rate	0.0001 ~ 0.080mm/s
Z-axis vertical fast-feed rate	50mm/s
Z-axis vertical-move minimum command unit	0.1 μm
Z-axis vertical-move minimum resolution	0.1 μm
Chuck table	
Bearing type	Air spindle
Chuck table type	Porous ceramics chuck table
Chuck method	Vacuum
Number of chuck table	3
Rotative speed	0 ~ 300 rpm(CCW/CW)
Chuck table washing	Brush cleaning/oil-stone cleaning
Air-bearing turntable	
Speed	0~300 rpm(CCW/CW)
Supporting method	Aerostatic
Positioning accuracy	0.1°
Height gauge	
Measuring range	0~2mm
Resolution	0.1 μm
Repeatability	$\pm 0.5 \mu\text{m}$
Dimensions	
(W×D×H)/mm	1415×3325×1820 mm
Weight	4.6t



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总公司：中国
先进微电子装备（郑州）有限公司
全球运营管理中心：中国上海ADT
 地址：上海浦东上科路88号西塔601
 电话：86-21-50939293
 传真：86-21-50939890
 E-mail: China_Marketing@adt-co.com

应用技术开发中心：
 地址：苏州市工业园区金鸡湖大道99号
 纳米城西北区20幢105室

中国台湾代表处：
 先进切割技术有限公司
 台湾新北市
 电话：886-2-2608-2027
 传真：886-2-2608-3710
 E-mail: adt-tw@adt-co.com

子公司：以色列
 先进切割技术有限公司
 HI-TECH PARK(SOUTH), PO BOX 87,
 YOKNEAM 2069202

电话：972-4-8545222
 传真：972-4-8550007
 E-mail: sales@adt-co.com

子公司：北美
 先进切割技术有限公司
 EAST COAST OFFICE - HORSHAM, PA
 电话：215-773-9155
 WEST COAST OFFICE - TEMPE, AZ
 电话：480-666-9620
 E-mail: adt-usa-sales@adt-co.com